



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD50N04S4-10		<b>Issued</b>		25. January 2018		
<b>MA#</b>		MA000788454						
<b>Package</b>		PG-TO252-3-313		<b>Weight*</b>		317.06 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.868	0.27	0.27	2738	2738
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		465	
	non noble metal	copper	7440-50-8	147.096	46.38	46.44	463940	464544
	non noble metal	aluminium	7429-90-5	1.631	0.51	0.51	5144	5144
wire	non noble metal	aluminium	7429-90-5	1.631	0.51	0.51	5144	5144
encapsulation	organic material	carbon black	1333-86-4	1.418	0.45		4472	
	plastics	epoxy resin	-	24.812	7.83		78257	
	inorganic material	silicondioxide	60676-86-0	115.554	36.45	44.73	364456	447185
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11796	11796
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4480	4491
solder	non noble metal	tin	7440-31-5	0.022	0.01		71	
	noble metal	silver	7440-22-4	0.028	0.01		88	
	non noble metal	lead	7439-92-1	1.071	0.34	0.36	3378	3537
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.05	6.06	60486	60565
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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